

## PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT7189817

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
AMRITA MATHURIYA	11/18/2021
CHRISTOPHER B. WILKERSON	10/10/2021
RAJEEV KUMAR DOKANIA	12/26/2021
DEBO OLAOSEBIKAN	09/24/2021
SASIKANTH MANIPATRUNI	11/18/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	KEPLER COMPUTING INC.
<b>Street Address:</b>	180 STEUART STREET
<b>Internal Address:</b>	#19254
<b>City:</b>	SAN FRANCISCO
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	94105
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17229754
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(971)634-0287
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	9716340286
<b>Email:</b>	docketing@impactpatents.com
<b>Correspondent Name:</b>	MUGHAL IP P.C.
<b>Address Line 1:</b>	1500 NW BETHANY BLVD.
<b>Address Line 2:</b>	SUITE 200
<b>Address Line 4:</b>	BEAVERTON, OREGON 97006
<b>ATTORNEY DOCKET NUMBER:</b>	12.P006US-CX1-C2
<b>NAME OF SUBMITTER:</b>	KATHERINE CAMPBELL
<b>SIGNATURE:</b>	/Katherine Campbell/
<b>DATE SIGNED:</b>	02/23/2022

**Total Attachments: 8**

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## **ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**Amrita Mathuriya, Christopher B. Wilkerson, Rajeev Kumar Dokania  
Debo Olaosebikan, Sasikanth Manipatruni**

hereby sell, assign, and transfer to:

### **Kepler Computing Inc.**

a corporation of Delaware, having a principal place of business at 180 Steuart Street #192524 San Francisco, CA 94105, USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

### **FERROELECTRIC MEMORY CHIPLET IN A MULTI-DIMENSIONAL PACKAGING WITH I/O SWITCH EMBEDDED IN A SUBSTRATE OR INTERPOSER**

**(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)**

which was filed on April 13, 2021 as

United States Application Number 17/229,754 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors,

assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Amrita Mathuriya  
Amrita Mathuriya

NOV 13, 2021  
Date signed

\_\_\_\_\_  
Christopher B. Wilkerson

\_\_\_\_\_  
Date signed

\_\_\_\_\_  
Rajeev Kumar Dokania

\_\_\_\_\_  
Date signed

\_\_\_\_\_  
Debo Olaosebikan

\_\_\_\_\_  
Date signed

Sasikanth Manipatrani  
Sasikanth Manipatrani

NOV 18, 2021  
Date signed

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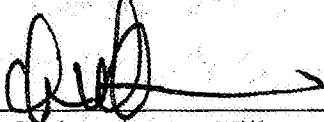
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Amrita Mathuriya



Christopher B. Wilkerson

Date signed

10/10/2021

Date signed

Rajeev Kumar Dokania

Date signed

Debo Olaosebikan

Date signed

Sasikanth Manipatruni

Date signed

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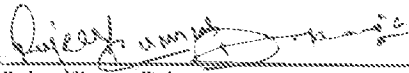
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Amrita Mathuriya

Date signed

Christopher B. Wilkerson

Date signed

  
Rajeev Kumar Dokania

12/26/2021  
Date signed

Debo Chakrabarti

Date signed

Sasikant Manipatruni

Date signed



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Debo

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Debo Olaosebikan

Date signed

Sasikanth Manipatruni

Date signed